

10 WATT POWER AMPLIFIER MODULE, 400 - 1000 MHz

Features

P1dB Output Power: 10 Watts
 Gain: 40 dB
 Output IP3: +54 dBm
 Single Positive Supply: +12V
 Thermally Compensated and Protected
 TTL DC Power Enable
 Unconditionally Stable
 Heat Sink/Fan Accessories Available

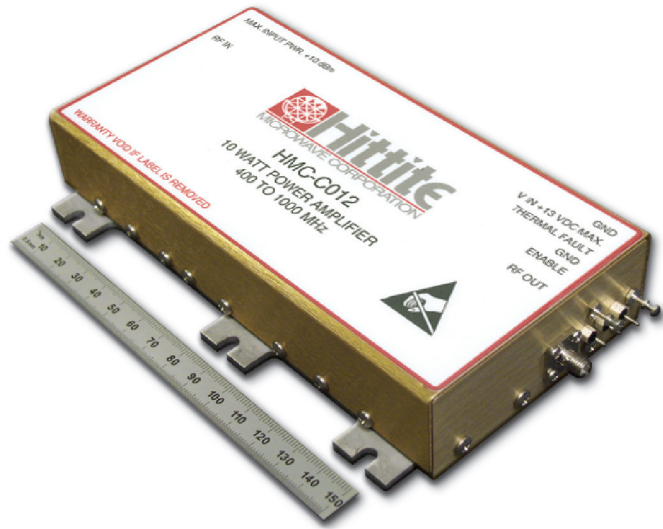
Typical Applications

The HMC-C012 is ideal for:

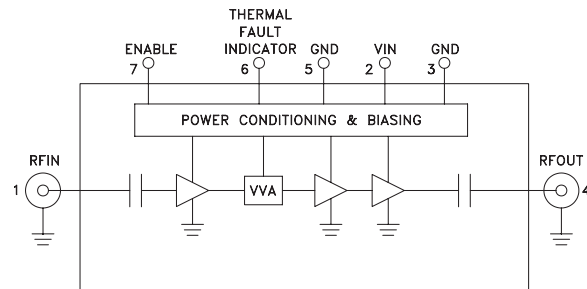
- Cellular/3G Infrastructure
- Automated Test Equipment (ATE)
- Laboratory Use

General Description

The HMC-C012 is a 10 Watt Power Amplifier Module suitable for Cellular/3G repeaters, wireless data, laboratory use and ATE applications. This extremely robust PA module is DC blocked, internally regulated and over voltage protected. Thermal protection/fault circuitry automatically turns off DC power if base temperature exceeds +75 °C and restores power at < +55 °C.



Functional Diagram

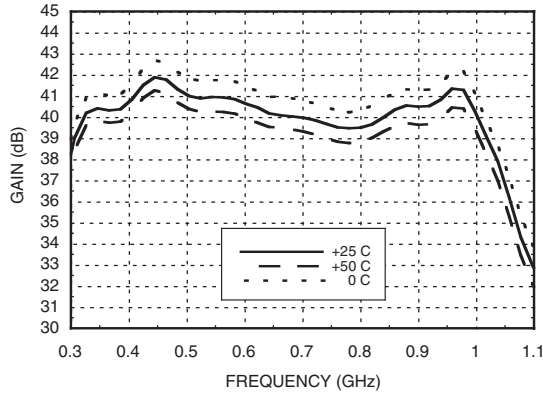


Electrical Specifications, $T_A = +25^\circ \text{C}$, $V_{IN} = +12\text{V}$

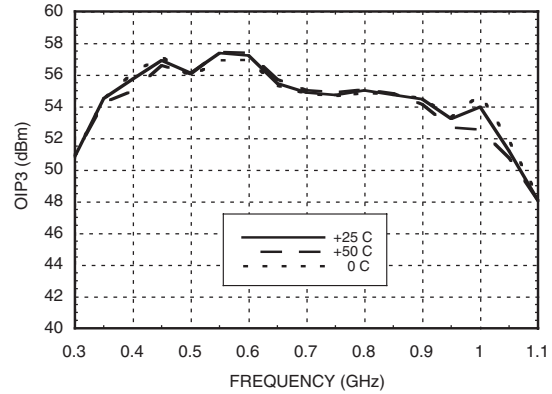
Parameter	Min.	Typ.	Max.	Units
Frequency Range	0.4 - 1.0			GHz
Gain	38	40		dB
Input Return Loss	9.5	12		dB
Output Return Loss	7.5	12		dB
Output Power for 1 dB Compression (P1dB)	9	10		W
Saturated Output Power (Psat)		42		dBm
Output Third Order Intercept (IP3) (Two-tone Input Power = -28 dBm each tone)		54		dBm
Channel Output Power for -60 dBc ACPR (CDMA-2000, 1.98 MHz offset)		36		dBm
Channel Output Power for -50 dBc ACPR (CDMA-2000, 885 kHz offset)		34		dBm
Second Harmonic at Output P1dB		-20		dBc
Third Harmonic at Output P1dB		-30		dBc
Spurious at Output P1dB		-65		dBc
Supply Current		6.5	7.0	A

**10 WATT POWER AMPLIFIER
MODULE, 400 - 1000 MHz**

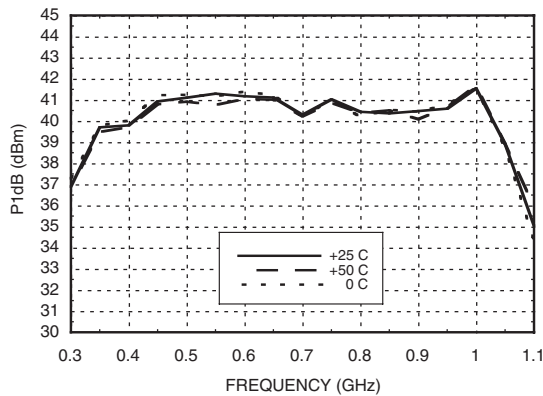
Gain vs. Temperature



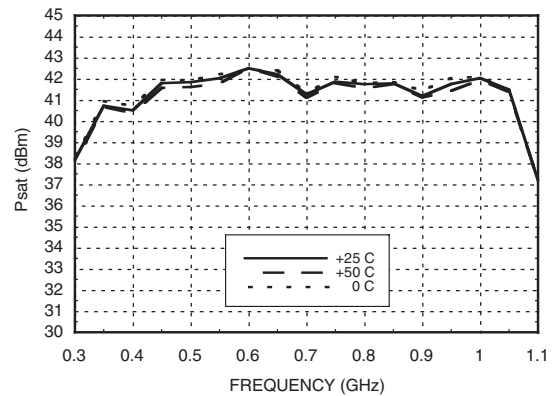
Output IP3 vs. Temperature



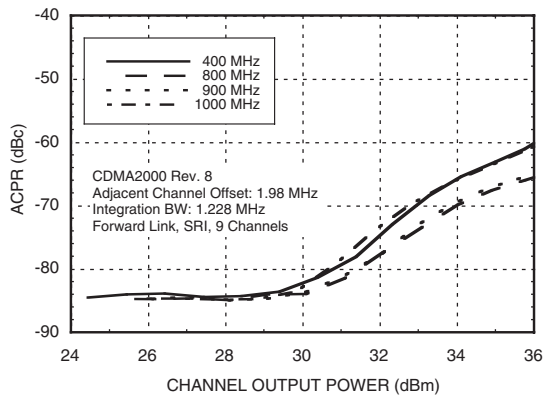
P1dB vs. Temperature



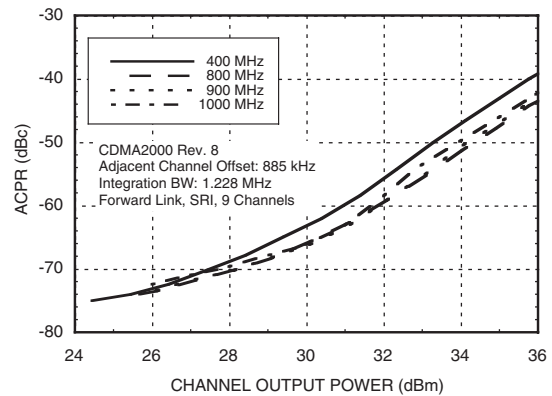
Psat vs. Temperature



ACPR, CDMA-2000, 1.98 MHz Offset

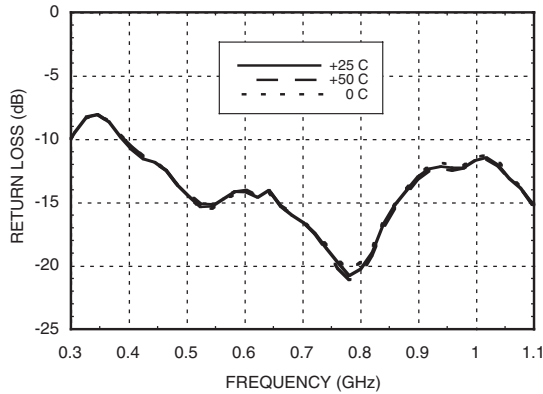


ACPR, CDMA-2000, 885 kHz Offset

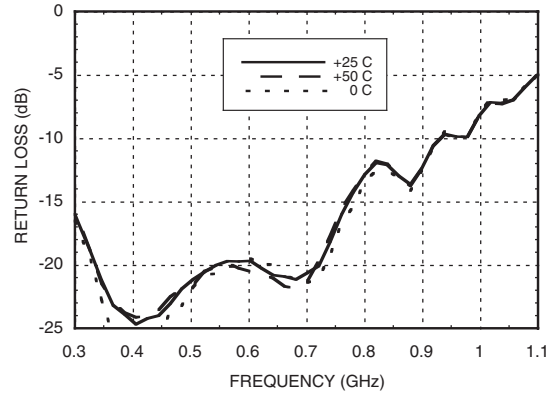


**10 WATT POWER AMPLIFIER
MODULE, 400 - 1000 MHz**

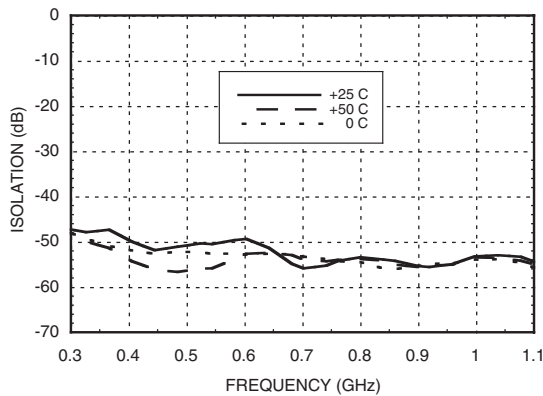
Input Return Loss vs. Temperature



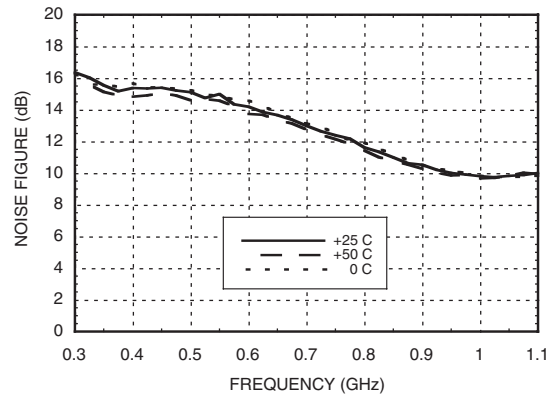
Output Return Loss vs. Temperature



Reverse Isolation vs. Temperature



Noise Figure vs. Temperature



Absolute Maximum Ratings

Supply Voltage (VIN)	+13 Vdc
RF Input Power (RFIN)	+10 dBm
Storage Temperature	-40 to +85 °C
Operating Temperature	0 to +50 °C
Thermal Fault Indicator Max Pdiss (derate 1.8 mW/°C above 50 °C)	180 mW
Enable	-0.5 to +6.0 Vdc

**Thermal Fault Indicator
Characteristics**

Parameter	Min.	Typ.	Max.	Units
I _{OUT} (V _{OUT} > 2V)		350		mA
R _{ON} (I _{OUT} = 50 mA)			7.5	Ohms
R _{OFF} (V _{OUT} = 30 V)		1		MOhm



**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**

Enable Input Characteristics

Parameter	Min.	Typ.	Max.	Units
V _{IH}	3.5			V
V _{IL}			1.6	V
I _{IL} @ VIN = 0V		-0.5		mA
I _{IH} @ 5V		< ± 50		µA

**10 WATT POWER AMPLIFIER
MODULE, 400 - 1000 MHz**

Recommended Biasing Procedure

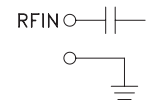
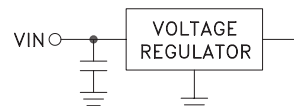

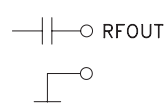

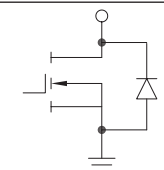
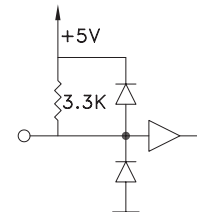
TURN-ON

1. Connect RF input and output
2. Apply Supply Voltage VIN (+12 Vdc)
3. Set Enable low
4. Apply RF input signal

TURN-OFF

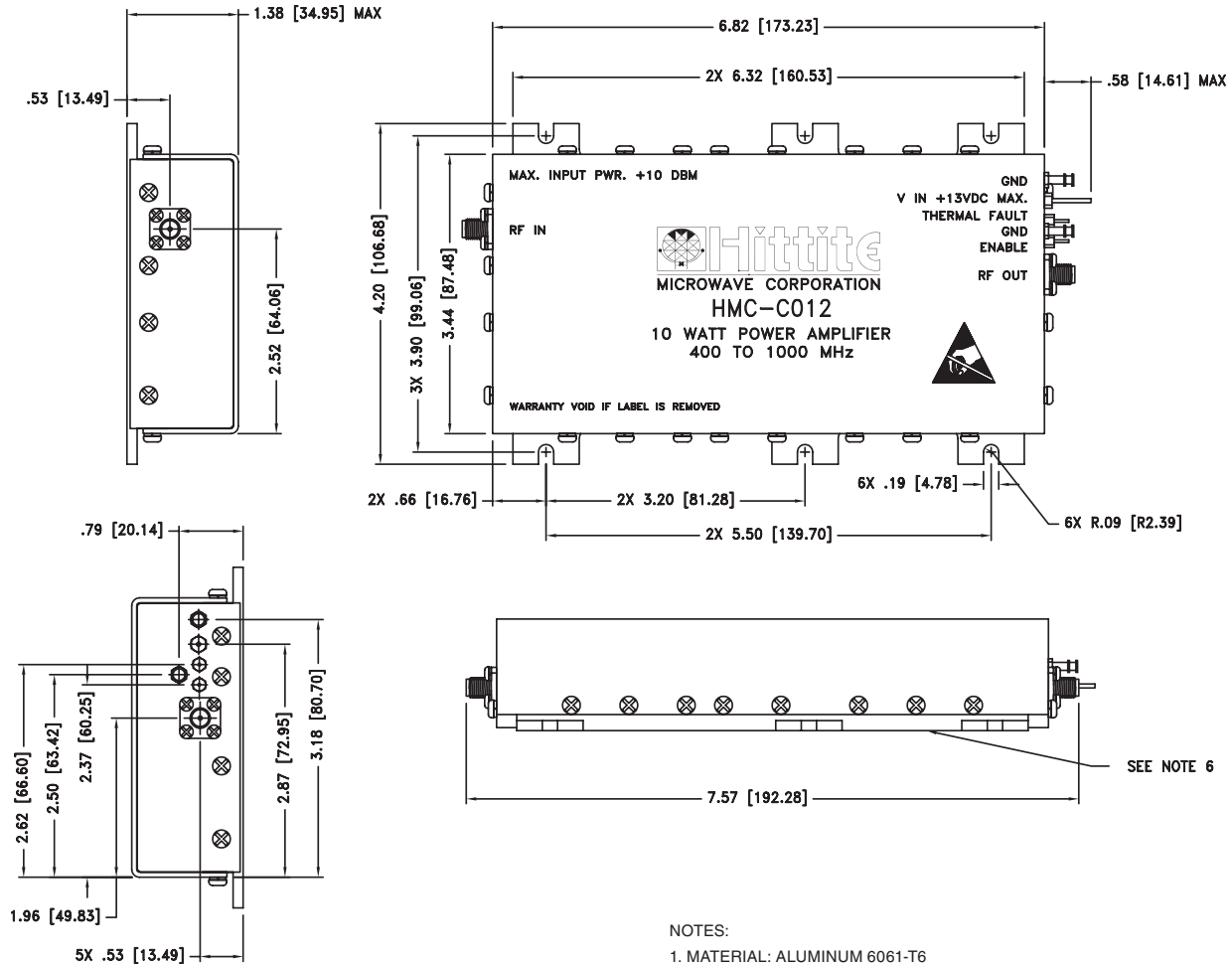
1. Remove RF input signal
2. Remove Supply Voltage VIN

Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1	RFIN & RF Ground	RF input connector, SMA female. This pin is AC coupled and matched to 50 Ohms from 400 - 1000 MHz.	
2	VIN	Power supply voltage for the amplifier.	
3	GND	Power supply ground.	
4	RFOUT & RF Ground	RF output connector, SMA female. This pin is AC coupled and matched to 50 Ohms from 400 - 1000 MHz.	
5	GND	Ground for thermal fault indicator and enable circuit.	
6	Thermal Fault Indicator	Open drain output. High impedance for base plate temperatures less than 55 °C. Low impedance for base plate temperatures exceeding 75 °C.	
7	Enable	TTL compatible supply voltage (VIN) shutdown. If enable feature is not required, short this pin to DC ground. TTL "High" Disable TTL "Low" Enable	

10 WATT POWER AMPLIFIER MODULE, 400 - 1000 MHz

Outline Drawing



NOTES:

1. MATERIAL: ALUMINUM 6061-T6
2. FINISH
 - a. COVER & END PLATES, CHEMICAL FILM PER MIL-C-5541, CLASS 3
 - b. BASE, TIN
3. RF CONNECTORS, SMA STYLE
4. DIMENSIONS ARE INCHES (MM)
5. TOLERANCES $.X \pm .1$ (2.54mm)
 $.XX \pm .02$ (0.50mm)
6. DRAWING TO CHANGE AS REQUIRED.
7. BASE MUST BE GROUNDED AND MOUNTED TO HEAT SINK CAPABLE OF DISSIPATING 100W (65 °C)

